

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (Cancelled)

2. (Previously Presented) Electrospray source according to claim 23, wherein the supply means comprise at least one reservoir in fluidic communication with the capillary slot.

3. (Cancelled)

4. (Previously Presented) Electrospray source according to claim 23, wherein the supply means comprise a reservoir constituted by a recess formed in said wafer and in fluidic communication with the capillary slot.

5. (Previously Presented) Electrospray source according to claim 23, wherein the means of applying an electrospray voltage comprise at least one electrode arranged so as to be in contact with said liquid to be nebulised.

6. (Previously Presented) Electrospray source according to claim 23, wherein the means of applying an electrospray voltage comprise the support, at least

partially electrically conductive, and/or the wafer at least partially electrically conductive.

7. (Previously Presented) Electrospray source according to claim 23, wherein the means of applying an electrospray voltage comprise an electrically conductive wire arranged in order to be able to be in contact with said liquid to be nebulised.

8. (Previously Presented) Electrospray source according to claim 23, wherein the supply means comprise a capillary tube.

9. (Previously Presented) Electrospray source according to claim 23, wherein the supply means comprise a channel formed in a microsystem supporting said structure and in fluidic communication with the capillary slot.

10. (Previously Presented) Electrospray source according to claim 23, wherein the wafer has a surface hydrophobic to the liquid to be nebulised.

11. (Currently Amended) Method of manufacturing a structure being an electrospray source, comprising:

- the formation of a support from a substrate, the support having a main face,
- the formation of a wafer having a part constituting a flat and thin tip, said tip comprising a first face and a second face and being provided with a capillary slot, to

convey a liquid to be nebulised, formed in a complete thickness of the tip from said first face through said second face and which ends up at an end of the tip,

- making said wafer integral on the main face of the support, the tip being cantilevered along a plane in relation to the support, wherein said thickness being substantially orthogonal to the plane.

12. (Previously Presented) Method according to claim 11, wherein it comprises the following steps:

- the provision of a substrate to form the support,
- the delimitation of the main face of the support by means of trenches etched in the substrate,
- the deposition, on a zone of the main face of the substrate corresponding to the future tip of the structure, of sacrificial material according to a determined thickness,
- the deposition of the wafer on the main face of the support delimited in the substrate, the tip of the wafer being situated on the sacrificial material,
- the elimination of the sacrificial material,
- the detachment of the support in relation to the substrate by cleavage at the level of said trenches.

13. (Previously Presented) Method according to claim 12, wherein the step of deposition of the wafer is a deposition of a wafer comprising a recess in fluidic communication with the capillary slot in order to constitute a reservoir.

14. (Previously Presented) Method according to claim 12, wherein it further comprises a step of depositing at least one electrode intended to assure an electrical contact with the liquid to be nebulised.

15. - 18. (Canceled)

19. (Previously Presented) Ionization of a liquid by electrospraying the liquid with the electrospray source of claim 23, and analyzing the changed liquid by mass spectrometry.

20. (Previously Presented) Producing drops of liquid of a calibrated or controlled size by electrospraying a liquid using the electrospray source of claim 23.

21. (Previously Presented) Carrying out molecular writing with chemical compounds by electrospraying chemical compounds using the electrospray source of claim 23.

22. (Previously Presented) Electrospraying a liquid using the electrospray source of claim 23 to define the electrical junction potential of a device in fluidic continuity.

23. (Currently Amended) Electrospray source having a structure which comprises:

a support having a main face;

a wafer formed on said main face of the support and integral with said main face of the support, a part of the wafer constituting at least one flat and thin tip cantilevered with respect to the support, said tip comprising a first face and a second face and being provided with a capillary slot formed through a complete thickness of the tip from said first face through said second face, said thickness being substantially orthogonal to the main face of the support, said capillary slot leading to an end of the tip to form an ejection orifice of the electrospray source, the electrospray source comprising means for supplying the capillary slot with liquid to be nebulised and means for applying an electrospray voltage to said liquid.